



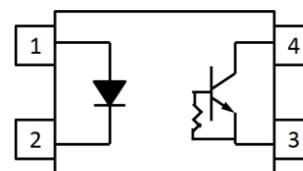
### 4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL2514-G Series



#### Features:

- Halogens free.  
(Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)
- Current transfer ratio(CTR: 50~200% at  $I_F = 5\text{mA}$ ,  $V_{CE} = 5\text{V}$ ,  $T_A = 25^\circ\text{C}$ )
- High isolation voltage between input and output ( $V_{iso} = 5000\text{Vrms}$ )
- High-Speed switching ( $t_{on} \leq 25 \mu\text{s}$  at  $I_F=5\text{mA}$ ,  $V_{CC}=5\text{V}$ ,  $R_L=5\text{k}\Omega$ ,  $T_A = 25^\circ\text{C}$ )  
( $t_{off} \leq 25 \mu\text{s}$  at  $I_F=5\text{mA}$ ,  $V_{CC}=5\text{V}$ ,  $R_L=5\text{k}\Omega$ ,  $T_A = 25^\circ\text{C}$ )
- Creepage distance > 7.62mm
- Operating temperature up to  $+110^\circ\text{C}$
- Compact small outline package
- Compliance with EU REACH
- The product itself will remain within RoHS compliant version
- UL and cUL (No.E214129)
- VDE approved (No.132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

#### Schematic



#### Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

#### Description

The EL2514-G series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector. The EL2514-G has enabled relatively high switching speed with high load resistor of several k $\Omega$ . They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

#### Applications

- Programmable controllers
- System appliances, measuring instruments
- Electronic electricity meter
- Telecommunication equipments
- Power supply

### Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward Current	I <sub>F</sub>	50	mA
	Peak Forward Current (1μs, pulse)	I <sub>FP</sub>	0.5	A
	Reverse Voltage	V <sub>R</sub>	6	V
Output	Collector Current	I <sub>C</sub>	20	mA
	Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
	Emitter-Collector Voltage	V <sub>ECO</sub>	0.45	V
Total Power Dissipation		P <sub>TOT</sub>	200	mW
Isolation Voltage* <sup>1</sup>		V <sub>ISO</sub>	5000	V <sub>rms</sub>
Operating Temperature		T <sub>OPR</sub>	-55 to +110	°C
Storage Temperature		T <sub>STG</sub>	-55 to +125	°C
Soldering Temperature* <sup>2</sup>		T <sub>SOL</sub>	260	°C

Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

\*2 For 10 seconds

### Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit
Input Current	I <sub>F</sub>	5	6	7	mA

**Electro-Optical Characteristics (Ta=25°C unless specified otherwise)**

**Input**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V <sub>F</sub>	-	1.2	1.4	V	I <sub>F</sub> = 20mA
Reverse Current	I <sub>R</sub>	-	-	10	μA	V <sub>R</sub> = 4V
Input Capacitance	C <sub>in</sub>	-	30	250	pF	V = 0, f = 1kHz

**Output**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter Dark Current	I <sub>CEO</sub>	-	-	100	nA	V <sub>CE</sub> = 10V, I <sub>F</sub> = 0mA
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	40	-	-	V	I <sub>C</sub> = 0.1mA
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	0.45	-	-	V	I <sub>E</sub> = 0.1mA

**Transfer Characteristics**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer Ratio	CTR	50	-	200	%	I <sub>F</sub> = 5mA, V <sub>CE</sub> = 5V
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	-	-	0.35	V	I <sub>F</sub> = 5mA, I <sub>C</sub> = 0.4mA
Isolation Resistance	R <sub>IO</sub>	5×10 <sup>10</sup>	-	-	Ω	V <sub>IO</sub> = 500Vdc, 40~60% R.H.
Floating Capacitance	C <sub>IO</sub>	-	0.6	1.0	pF	V <sub>IO</sub> = 0, f = 1MHz
Turn-on Time	t <sub>on</sub>	-	-	25	μs	V <sub>CC</sub> = 5V, I <sub>F</sub> = 5mA,
Turn-off Time	t <sub>off</sub>	-	-	25	μs	R <sub>L</sub> = 5kΩ

\* Typical values at T<sub>a</sub> = 25°C

Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs. Forward Voltage

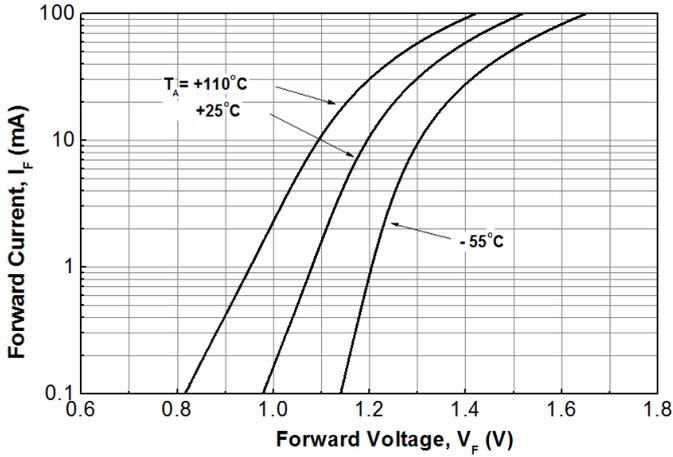


Figure 2. Current Transfer Ratio vs Forward Current

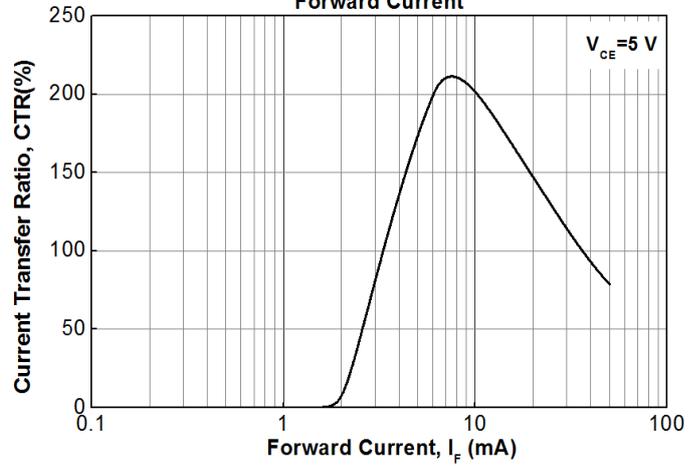


Figure 3. Current Transfer Ratio vs Ambient Temperature

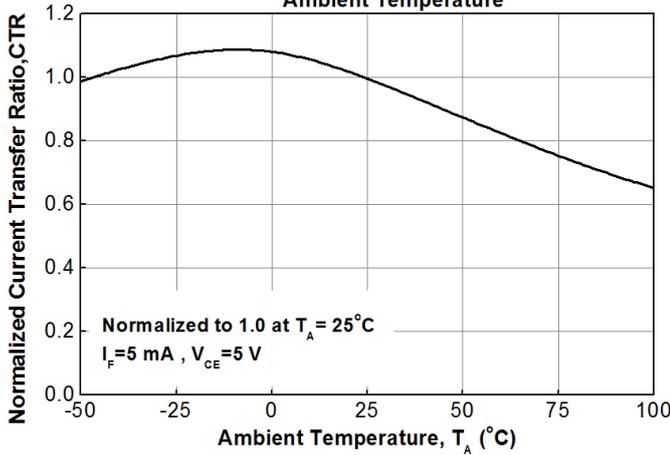


Figure 4. Dark Current vs Ambient Temperature

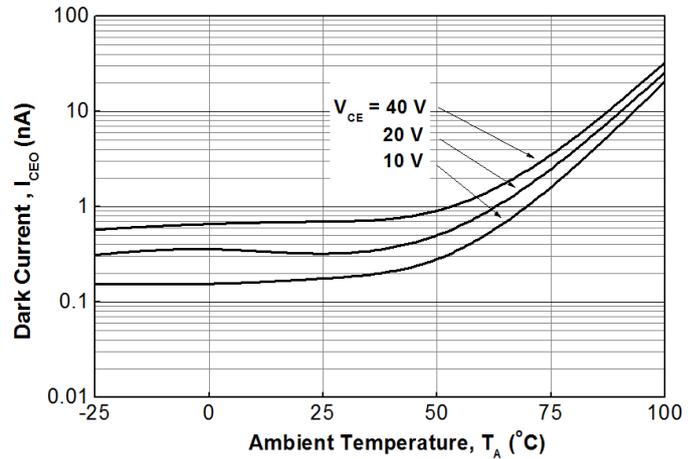


Figure 5. Collector Current vs Collector Saturation Voltage

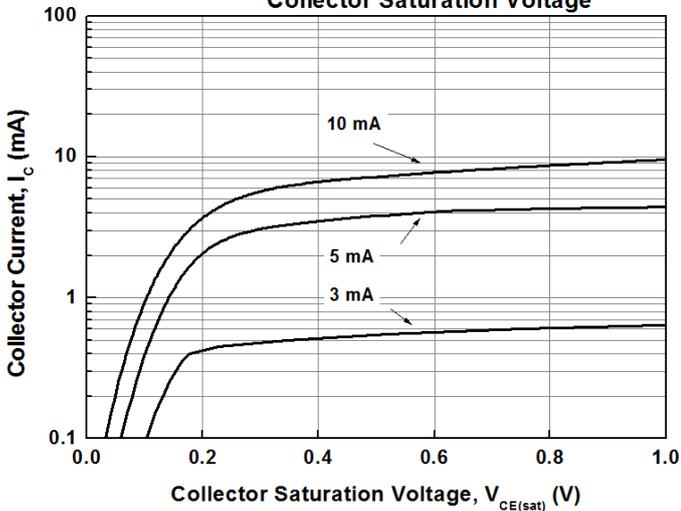
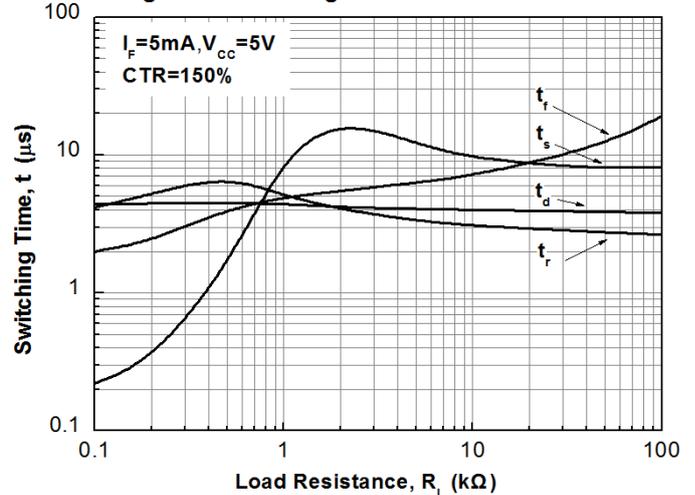


Figure 6. Switching Time vs Load Resistance



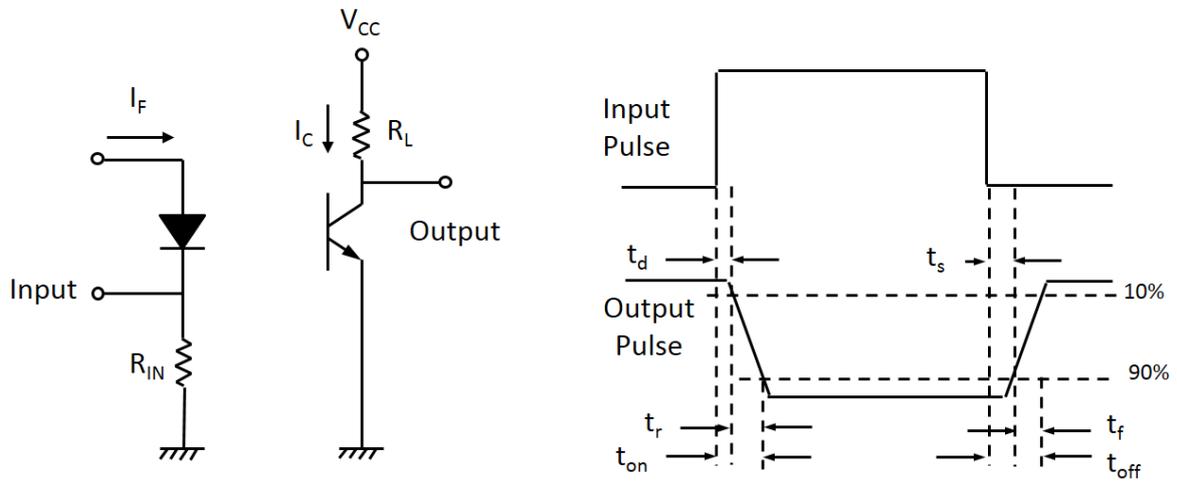


Figure 7. Switching Time Test Circuit & Waveforms

## Order Information

### Part Number

# EL2514X(Y)-VG

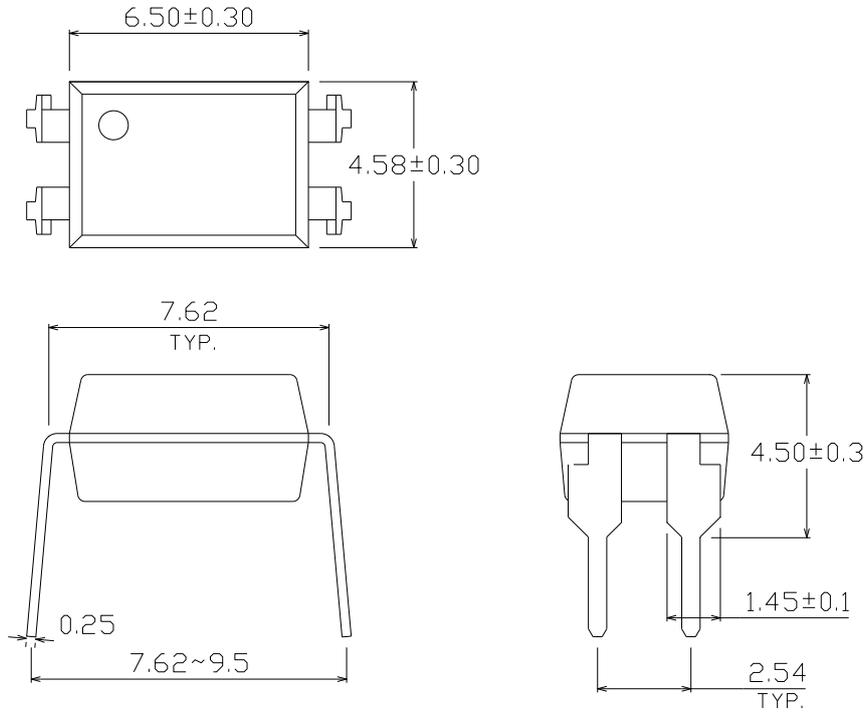
#### Note

- X = Lead form option (S1, S2, M or none)
- Y = Tape and reel option (TU, TD or none)
- V = VDE safety (optional)
- G = Halogens free

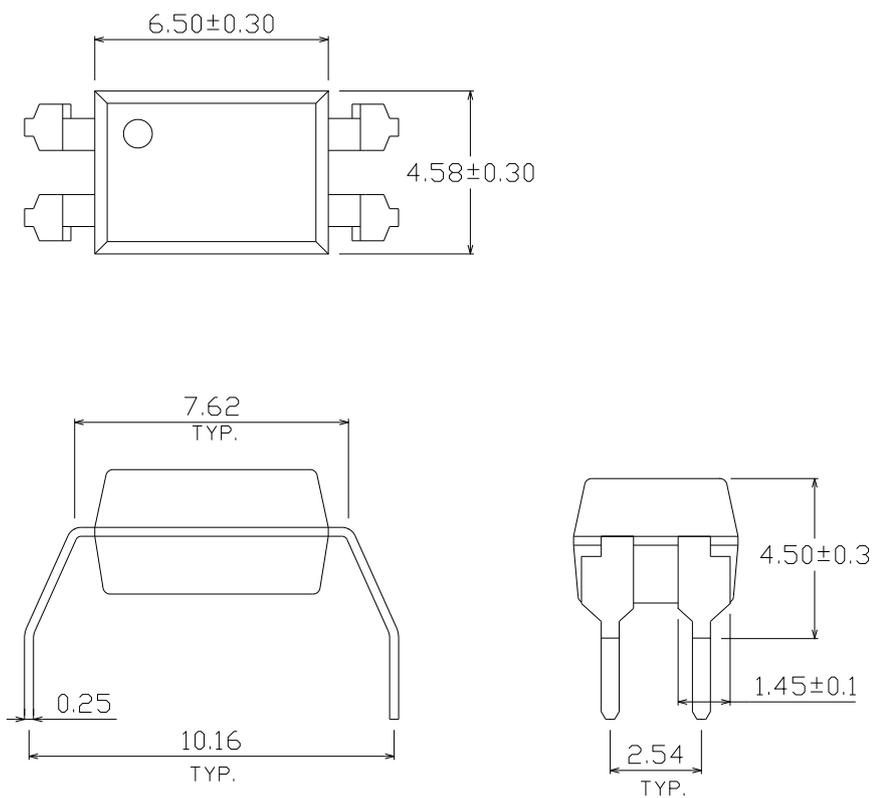
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

**Package Dimension (Dimensions in mm)**

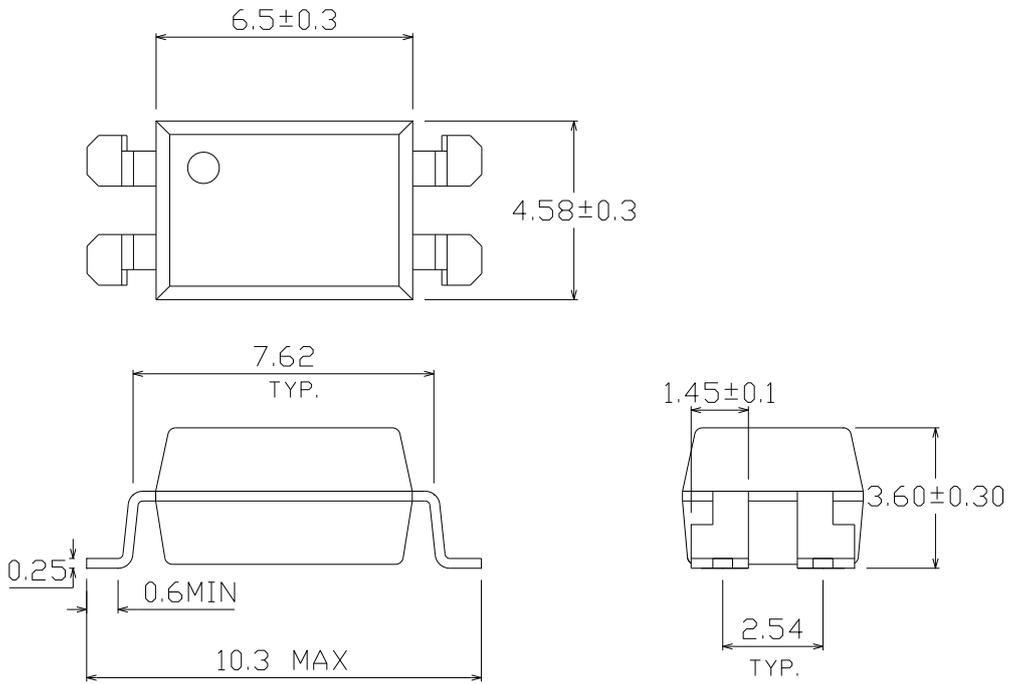
**Standard DIP Type**



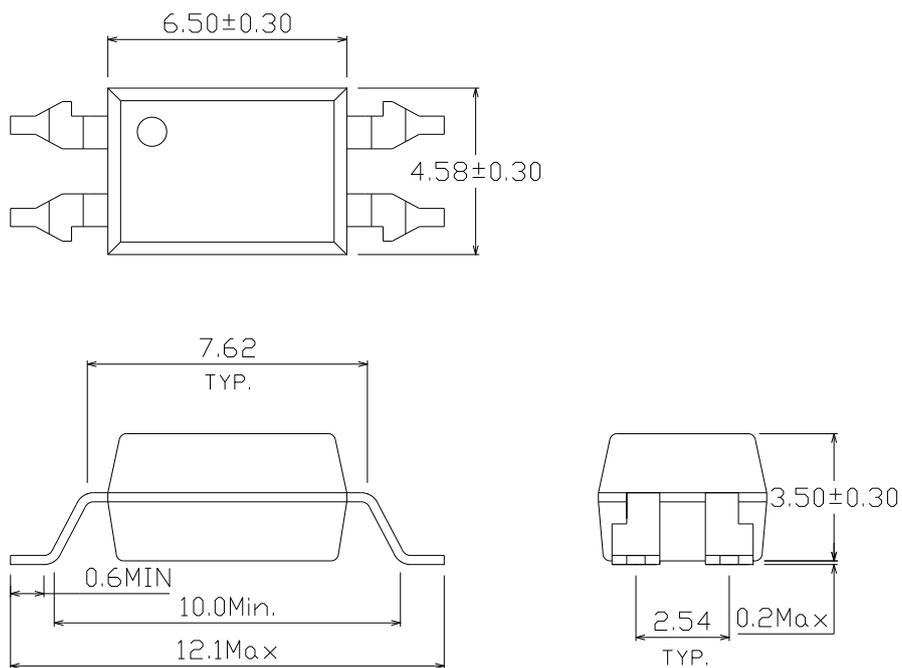
**Option M Type**



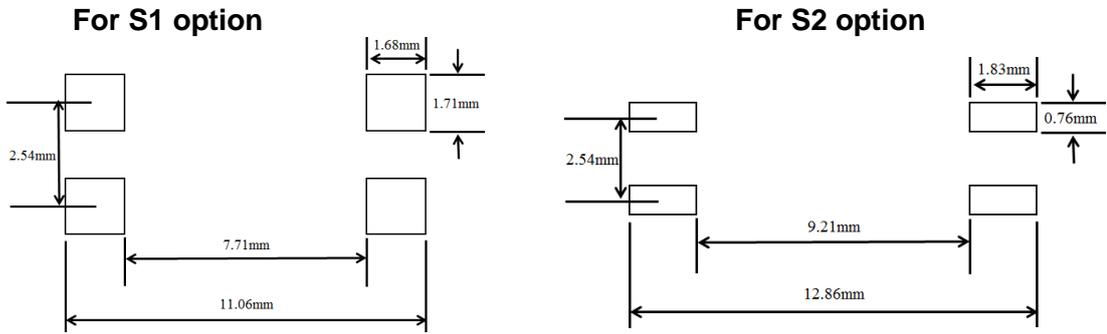
**Option S1 Type**



**Option S2 Type**



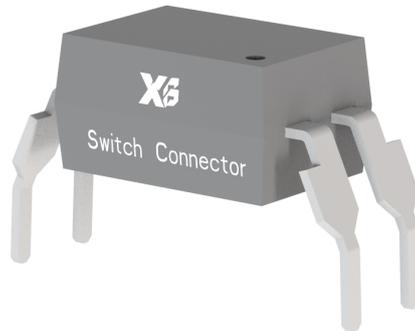
### Recommended pad layout for surface mount leadform



### Notes

Suggested pad dimension is just for reference only.  
Please modify the pad dimension based on individual need.

### Device Marking

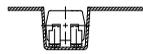
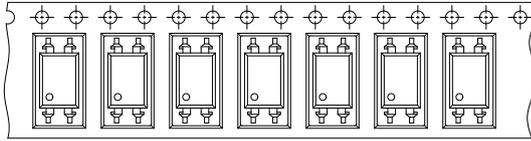


### Notes

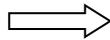
EL denotes XI BNANG 2514  
denotes Device Number G  
denotes Green part Y  
denotes 1 digit Year code WW  
denotes 2 digit Week code V  
denotes VDE (optional)

### Tape & Reel Packing Specifications

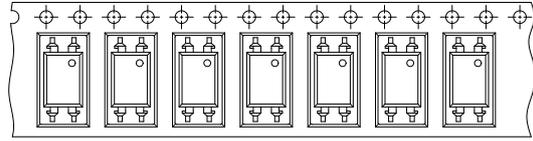
#### Option TD



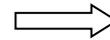
Direction of feed from reel



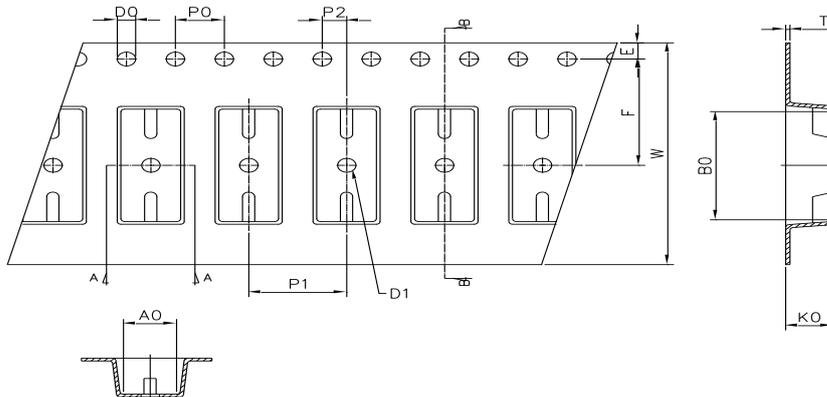
#### Option TU



Direction of feed from reel



### Tape dimensions

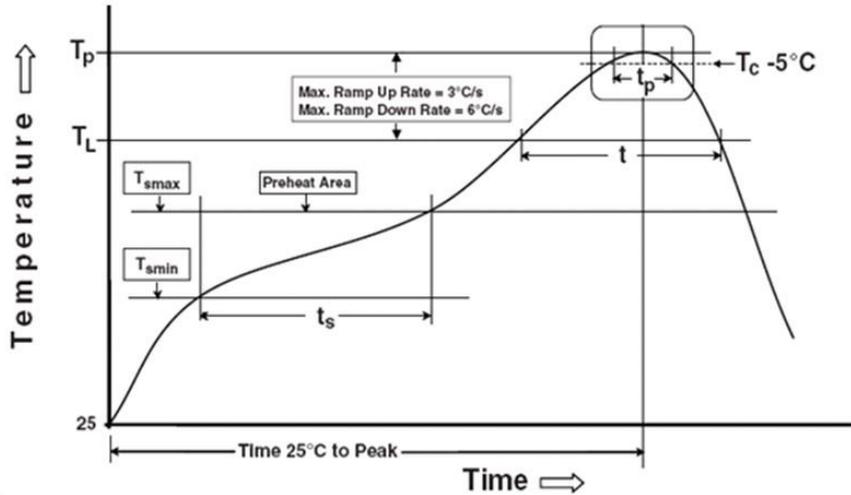


Dimension No.	<b>Ao</b>	<b>Bo</b>	<b>Do</b>	<b>D1</b>	<b>E</b>	<b>F</b>
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	<b>Po</b>	<b>P1</b>	<b>P2</b>	<b>t</b>	<b>W</b>	<b>Ko</b>
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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